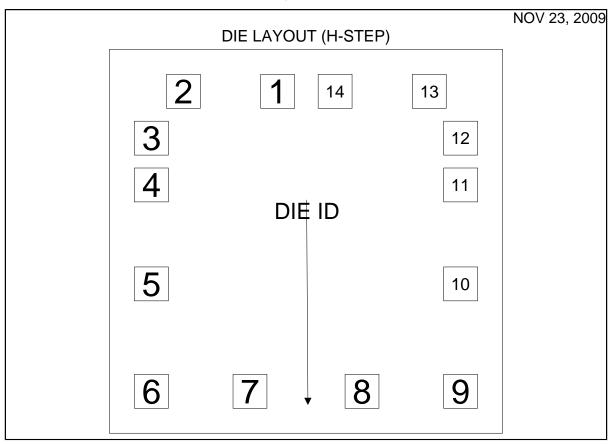


LM139 MDE SMD#5962R9673802V9A LOW POWER LOW OFFSET VOLTAGE QUAD COMPARATOR



DIE/WAFER CHARA	CTERISTICS			
Fabrication Attributes		General Die Information		
Physical Die	1901H	Bond Pad Opening 92.00µm x 92.		
Identification		Size (min)		
Die Step	Н	Bond Pad Metalization	AL 0.5%CU	
Physical Attributes		Passivation	VOM ONLY	
Wafer Diameter	150mm	Back Side Metal	BAREBACK	
Die Size (Drawn)	1066.8µm x 1041.4µm	Back Side Connection	Floating or GND	
	42.0mils x 41.0mils			
Thickness	330µm Nominal			
Min Pitch	127.00µm			
Note: All values are roun	ded to the nearest micron	•		
Special Assembly Requir	rements:			



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Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		Χ	Υ	Χ		Υ
Output 2	1	-77	407	92	Х	92
Output 1	2	-333	407	92	х	92
V +	3	-420	280	92	Х	92
- Input 1	4	-420	153	92	Х	92
+ Input 1	5	-420	-116	92	Х	92
- Input 2	6	-420	-407	92	Х	92
+ Input 2	7	-152	-407	92	Х	92
- Input 3	8	152	-407	92	Х	92
+ Input 3	9	420	-407	92	Х	92
- Input 4	10	420	-116	92	Х	92
+ Input 4	11	420	153	92	х	92
GND	12	420	280	92	Х	92
Output 4	13	335	407	92	Χ	92
Output 3	14	79	407	92	Х	92



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